



### DESCRIPTION OF CLAIM AMENDMENTS

Claims 26, 42, and 53 are amended as follows. Added language is underlined; deleted language is in brackets.

26. (amended) A method for producing an *in-situ* composite solder having an intermetallic component, comprising the steps of:

- (a) providing a matrix solder comprising two [or more] metals;
- (b) heating a mixture of said matrix solder with [the components of] said intermetallic component at a temperature greater than the highest melting temperature of any of the individual components of said mixture so as to form a non-solid mixture; and
- (c) cooling said non-solid mixture at a rate of at least about 100°C/second.

42. (amended) A method for producing an *in-situ* composite solder having an intermetallic component, comprising the steps of:

- (a) providing a matrix solder comprising two [or more] metals;
- (b) heating a mixture of said matrix solder with [the components of] said intermetallic component at a temperature greater than the highest melting temperature of any of the individual components of said mixture so as to form a non-solid mixture;
- (c) cooling said non-solid mixture to form a solid mixture;
- (d) heating said solid mixture formed in step (c) to a temperature greater than the melting point of the components of said intermetallic component; and
- (e) cooling the heated mixture of step (d) at a rate of at least about 100°C/second.

53. (amended). A method for producing an *in-situ* composite solder having an intermetallic component, comprising the steps of:

- (a) providing a binary or ternary [matrix] eutectic or near eutectic matrix solder;
- (b) heating a mixture of said matrix solder with [the components of a] an intermetallic component comprising a first row transition metal, at a temperature greater than the highest melting temperature of any of the individual components of said mixture so as to form a non-solid mixture; and
- (c) cooling said non-solid mixture at a rate of at least about 100°C/second to form said composite solder wherein said intermetallic component has a particle size less than about 10 microns.